

Meeting Minutes: IEEE PLCA Enhancements Study Group

September 14, 15, and 16, 2026
In-Person w/Remote Access Interim, Lisbon, Portugal
(IEEE 802.3 Interim Meeting Series)

Prepared by Natalie Wienckowski

See Appendix A for Attendance

IEEE P802.3dm Task Force meeting convened at **8:15 AM WEST, Monday, September 14, 2026**, by Yong Kim, IEEE PLCA Enhancements SG Chair Pro Tem.

ALL TIMES ARE IN WEST.

Mr. Kim turned to presentation [agenda_eplca_01a_2609.pdf](https://ieeep802.org/3/EPLCA/public/2609/agenda_eplca_01a_2609.pdf) and reviewed the agenda for the meeting.

Presentation: https://ieeep802.org/3/EPLCA/public/2609/agenda_eplca_01a_2609.pdf

Presenter: Yong Kim, Chair Pro Tem

(NOTE – the presentation “agenda_eplca_01a_2609.pdf” or updates will be referred to as “the agenda deck” in these minutes.)

Approval of Agenda: The chair asked whether there were additions or corrections to the agenda, shown on slide 3 of the presentation [agenda_eplca_01a_2609.pdf](https://ieeep802.org/3/EPLCA/public/2609/agenda_eplca_01a_2609.pdf). He then asked if there were any objections to approving the agenda. There were none. **(8:33 AM)**

The Chair then resumed the review of the agenda deck.

Mr. Kim noted that there should be no recording or photography without permission.

Mr. Kim asked if anyone was attending from the press including those who would run a public blog on this meeting – there were no indications from the group. **(8:36 AM)**

The chair discussed decorum and processes for joining the queue using the conference tool.

The chair discussed the goals of the meeting, which were resolution of comments on the task force review draft 0d, create D2.0 for WG ballot, and progress the draft to the working group for consideration of initial Working Group Ballot.

Mr. Kim then continued review of the presentation, reviewing information for the reflector and ground rules.

The Chair announced that under 802.3 rules, anyone in the meeting could vote on Motions or straw polls in a SG. In the agenda deck she provided a link to the IEEE 802.3 Ethernet Working Group Operations Manual for further information.

Attendance

The chair reminded the group that attendance would be taken from Webex as IMAT was not up. He then reminded attendees that they should show their employer & affiliation, and how to set these to make them correct. **(8:48)**

(8:58) IMAT was working so all attendees were requested to log their attendance. There were no participants that indicated they could not log their attendance in IMAT.

IEEE Structure, Policies

Mr. Kim continued review of the IEEE SA structure, where to find the bylaws, policies & procedures documents, and operations manuals which hierarchically govern IEEE SA, IEEE 802 LMSC, and IEEE 802.3 activities.

Mr. Kim showed the policy slides which start on page 25 of https://www.ieee802.org/3/EPLCA/public/2609/agenda_eplca_01b_2609.pdf and gave a brief summary.

There were no questions.

Mr. Kim reviewed the standards development process for IEEE 802.3 and where this Task Force is in that process.

He briefly went over the study group rules and goals slides (18-20).

PRESENTATIONS

(9:11)

Title: Project documents: Overview and Guidance

URL:

Presenter: Adam Healey (Broadcom)

Discussion: The presenter discussed what is documents the SG needs to create, and suggestions for what to include, in order to request to become a TF.

Questions were asked and answered.

(9:46)

Title: E-PLCA Timeline Proposal

URL: https://www.ieee802.org/3/EPLCA/public/2609/kim_eplca_04b_2609.pdf

Presenter: Yong Kim (GM)

Discussion: The presenter shared an aspirational timeline to get to WG ballot in November 2027.

There were no questions.

Following the presentation, the meeting recessed for the morning break **(9:57 AM)**

The Chair pro tem called the meeting back to order at **10:22 AM**.

(10:23)

Title: Differentiated Services on Half-Duplex Media

URL: https://www.ieee802.org/3/EPLCA/public/2609/jones_eplca_01_2609.pdf

Presenter: Peter Jones (Cisco)

Discussion: The presenter discussed issues with current PLCA and potential ways to improve them.

Questions were asked and answered.

During his presentation, the presenter shared parts of a white paper that explains the issue in more detail:

https://www.ieee802.org/3/EPLCA/public/2609/jones_eplca_02_2609.pdf.

(11:15)

Title: Differentiated Services on Half-Duplex Media

URL: https://www.ieee802.org/3/EPLCA/public/2609/Zimmerman_Baggett_eplca_01a_2609.pdf

Presenter: Tim Baggett (Microchip)

Discussion: The presenter discussed what was changed from 802.3cg for 802.3da, including PLCA and D_PLCA.

Questions were asked and answered.

During the presentation, the Chair asked everyone to sign into IMAT. No one indicated an issue with doing so.

At 12:03 PM the meeting recessed to resume Tuesday 9/15 at 8:00 AM.

At 8:05 AM on 9/15 Mr. Kim, the Chair Pro Tem, called the meeting to order.

Mr. Kim informed the group that he had received a late presentation and asked the group if there was any objection to hearing this during the meeting. There was no objection.

PRESENTATIONS

(8:08)

Title: Enhanced PLCA for Humanoid Robots

URL: https://iee802.org/3/EPLCA/public/2609/Mecklenburg_Lou_eplca_01_2609.pdf

Presenter: Ben Mecklenburg (Huawei)

Discussion: The presenter discussed the potential application of SPE and Enhanced PLCA for humanoid robots.

Questions were asked and answered.

Mr. Kim asked that people review the white paper by Peter Jones and contact him with any questions:

https://www.ieee802.org/3/EPLCA/public/2609/jones_eplca_02_2609.pdf

(8:32)

Title: Cyclic Traffic Requirements and the Time Axis in PLCA

URL: https://www.ieee802.org/3/EPLCA/public/2609/park_eplca_01c_2609.pdf

Presenter: Pusik Park (KETI (Korea Electronics Technology Institute))

Discussion: The presenter discussed the use of cyclic traffic with PLCA.

Questions were asked and answered.

(8:54) Everyone was asked to sign in to IMAT. No one indicated that they had an issue with doing so.

(8:56)

Title: Deterministic Latency Simulations

URL: https://www.ieee802.org/3/EPLCA/public/2609/DiBella_kim_eplca_01a_2609.pdf

Presenter: Yong Kim (General Motors)

Discussion: The presenter shared simulation results of “modulo” schemes to determine the potential impact on bounding latency.

Questions were asked and answered.

There was a question on slide 17 as to whether the measurement was at the RS layer or the application.

(9:34)

Discuss timeline https://www.ieee802.org/3/EPLCA/public/2609/kim_eplca_04c_2609.pdf

There was no objection to work to meet the proposed October pre-submissions of the PAR and CSD, including potential Web based Interims.

(9:44)

Discuss PAR document: https://iee802.org/3/EPLCA/public/2609/kim_eplca_03_2609.pdf

Mr. Kim updated the PAR during the discussion. See the results of this discussion in the updated PAR proposal. https://www.ieee802.org/3/EPLCA/public/2609/PAR-draft_eplca_2609a.pdf

During the PAR discussion, the meeting recessed for the morning break **(10:00 AM)**

The Chair pro tem called the meeting back to order at **10:22 AM** and resumed discussion on the PAR document.

(11:53) Everyone was asked to sign in to IMAT. No one indicated that they had an issue with doing so.

At 11:54 PM the meeting recessed to resume Wednesday 9/16 at 8:00 AM.

At 8:04 AM on 9/16 Mr. Kim, the Chair Pro Tem, called the meeting to order.

(8:07)

Discuss CSD document: https://ieee802.org/3/EPLCA/public/2609/kim_eplca_01_2609.pdf

Mr. Kim updated the CSD during the discussion. See the results of this discussion in the updated CSD proposal:

(9:40)

Discuss PAR document: https://www.ieee802.org/3/EPLCA/public/2609/kim_eplca_03_2609.pdf

Mr. Kim updated the PAR during the discussion. See the results of this discussion in the updated PAR proposal: https://www.ieee802.org/3/EPLCA/public/2609/PAR-draft_eplca_2609a.pdf, and https://www.ieee802.org/3/EPLCA/public/2609/CSD-draft_eplca_02609a.pdf.

(9:51) The meeting went on break.

(10:30) The meeting resumed.

Mr. Kim announced we would review the PAR and CSD responses with Mr. Law to ensure there are no issues with the wording.

The group continued to discuss the CSD after Mr. Law.

The updated PAR and CSD, for pre-submittal can be found:

https://www.ieee802.org/3/EPLCA/public/2609/PAR-draft_eplca_2609b.pdf, and https://www.ieee802.org/3/EPLCA/public/2609/CSD-draft_eplca_02609b.pdf.

(11:23) Motion #1

Move to approve the draft PAR and draft CSD responses, PAR-draft_eplca_2609b.pdf and CSD_draft_eplca_2609b.pdf.

M: Tim Baggett

S: Johannes Specht

Technical (>=75%)

Motion passes by voice without opposition.

(11:32) The Chair reminded participants to sign into IMAT and paused, asking if there were any individuals needing assistance recording their attendance.

The Chair returned to the agenda deck, and reviewed additional future meetings.

Future Meetings

Ad hocs: October 1 and 22, 7:00 – 9:00 am PDT to work on project objectives and any other work in support of project documentations.

(Hybrids)

802.3 PLCA Enhancement SG (eplca) will meet at the IEEE 802 Plenary in Bangkok, the week of November 9-12, exact days to be announced on the reflector. Registration and payment of a fee is required.

The Chair reminded participants to sign into IMAT and paused, asking if there were any individuals needing assistance recording their attendance.

CLOSING

The Chair announced that having exhausted the agenda, the meeting was adjourned. **(11:47 AM)**

Appendix A: Attendees at the IEEE P802.3dm Asymmetrical Electrical Automotive Ethernet Task Force Meeting, May 13-15, 2026. **imat based attendance (official record) will be posted when received.**

Topic			Total number of Attendees per day		
802.3 E-PLCA Study Group Sept 2026 Interim			40	39	46
FirstName	LastName	Affiliation	Online Attendance (zoom)		
			13-Sep	14-Sep	15-Sep
Shiju	Abraham	Acsia Technologies			Y
Ramanjit	Ahuja	Onsemi	Y	Y	
Tim	Baggett	Microchip	Y	Y	Y
Saied	Benyamin	Ethernovia		Y	Y
Karl	Budweiser	BMW		Y	Y
Valliappan	C	Acsia Technologies			Y
Lu	Chao	BMW		Y	
Lihao	Chen	Huawei		Y	
Xiaoyue	Cheng	Infineon	Y	Y	Y
Ian	Cox	Amazon		Y	
Shaoan	Dai	Infineon		Y	Y
Andras	de Koos	Microchip		Y	
Jonas	Edele	BMW	Y	Y	Y
Mohamed	Elattar	Huawei	Y	Y	Y
James	Gilb	GA-ASI	Y		
Steve	Gorshe	Microchip			Y
Marty	Gubow	Keysight			Y
Anil Sahul	Hameed	Acsia Technologies			Y
Adam	Healey	Broadcom	Y		
Thomas	Hogenmüller	Robert Bosch	Y		Y
Chad	Jones	Cisco			Y
Peter	Jones	Cisco	Y	Y	Y
Ragnar	Jonsson	Infineon	Y	Y	Y
Gloria	Joseph	Acsia Technologies			Y
DoKyun	Kim	LGE	Y	Y	Y
Gyudong	Kim	Analog Devices	Y	Y	Y
Yong	Kim	GM	Y	Y	Y
Jörg	Kock	NXP	Y	Y	Y
Ariel	Lasry	Qualcomm	Y	Y	Y
Ching-Yen	Lee	Realtek	Y	Y	Y
Dongjae	Lee	NEWRACOM			Y
YK	Lin	Realtek	Y	Y	Y
William	Lo	Axonne	Y		

Lily (Yunping)	Lyu	Huawei		Y	
Valerie	Maguire	Copperopolis	Y		
Ben	Mecklenburg	Huawei	Y	Y	Y
Scott	Muma	Microchip	Y	Y	Y
Martin	Ostertag	ZHAW]	Y		
Debajyoti (Debu)	Pal	onsemi		Y	Y
Sujan	Pandey	Velinktech	Y	Y	Y
Pusik	Park	KETI	Y	Y	Y
Alon	Regev	Keysight	Y	Y	Y
Anton	Schedl	BMW	Y	Y	Y
Johannes	Specht	Jspecht Consulting	Y	Y	Y
Heiko	Strohmeier	Bosch	Y	Y	Y
jingcong	Sun	motorcomm	Y	Y	Y
Wensheng	Sun	Credo			Y
Yuxuan	Tan	Motorcomm	Y	Y	Y
Geoff	Thompson	GraCaSI S.A.	Y	Y	Y
Luisma	Torres	KD	Y		
Max	Turner	Ethernovia	Y	Y	Y
Peter	van Dyck	Infineon			Y
Gumersindo	Veloso	BMW			Y
Bob	Voss	Panduit	Y		
Frank,	Wang	Realtek	Y	Y	Y
Terry	Wei	ADI	Y		
Natalie	Wienckowski	IVN Solutions	Y	Y	Y
James	Withey	Fluke	Y		
Dance	Wu	Infineon			Y
Conrad	Zerna,	NXP			Y
Dolly , Yue	Zhu	Huawei	Y	Y	Y
Yan	Zhuang	Huawei	Y	Y	

IMAT Attendance

			9/14/26	9/14/26	9/15/26	9/15/26	9/16/26	9/16/26
Last Name	First Name	Affiliation	AM1	AM2	AM1	AM2	AM1	AM2
Abraham	Shiju	Acsia Technologies					X	X
Ahuja	Ramanjit	ON Semiconductor	X	X	X	X	X	X
Baggett	Tim	Microchip Technology, Inc.	X	X	X	X	X	X
Benyamin	Saied	Ethernovia			X	X	X	X
Budweiser	Karl	BMW AG; BMW Group				X	X	X
Chen	Lihao	Huawei Technologies Co., Ltd			X			

cheng	xiaoyue	Infineon Technologies	X	X	X	X	X	
Chidambaram	Valliaappan	Acsia Technologies					X	X
Cox	Ian	Broadcom Corporation			X	X		
Dai	Shaoan	Infineon Technologies			X	X	X	X
de Koos	Andras	Microchip Technology Inc			X			
Edele	Jonas	BMW AG; BMW Group		X	X	X	X	X
Elattar	Mohamed	Huawei Technologies Duesseldorf GmbH	X	X	X	X	X	X
Gilb	James	General Atomics Aeronautical Systems, Inc.		X				
Gorshe	Steven Scott	Microchip Technology, Inc.					X	X
Gubow	Martin	Keysight Technologies		X	X	X	X	X
Hameed	Anil	Acsia Technologies					X	X
Healey	Adam	Broadcom Inc.	X					
Hogenmueller	Thomas	Robert Bosch GmbH						X
Jones	Chad	Cisco Systems, Inc.		X			X	
Jones	Peter	Cisco Systems, Inc.	X	X		X	X	X
Jonsson	Ragnar	Marvell	X	X		X	X	X
Joseph	Gloria	Acsia Technologies				X	X	X
Kim	DoKyun	LG ELECTRONICS	X	X	X	X	X	X
Kim	Gyudong	Analog Devices Inc.					X	X
Kim	Yongbum	General Motors Company	X	X	X		X	X
Kock	Joerg	NXP Semiconductors	X	X	X	X	X	X
Lasry	Ariel	Qualcomm Technologies, Inc	X	X	X	X	X	X
Lee	Ching-Yen	Realtek Semiconductor Corp.	X	X	X		X	
Lee	Dongjae	Newracom Inc.					X	X
Lin	YK	Realtek Semiconductor Corp.	X	X	X		X	
Lo	William	Axonne Inc.	X	X	X	X	X	X
Lyu	Yunping(Lily)	Huawei Technologies Co., Ltd			X	X		
Maguire	Valerie	Copperopolis (aff'l with CME Consulting and Microchip)	X	X	X	X	X	X
Marks	Roger	EthAirNet Associates		X				
Mecklenburg	Ben	Huawei Technologies Duesseldorf GmbH	X	X	X	X	X	X
Mellitz	Richard	Samtec, Inc.					X	
Muma	Scott	Microchip Technology, Inc.	X	X	X	X	X	X
Ostertag	Martin	ZHAW Zurich University of Applied Sciences	X					
Pal	Debajyoti	ON Semiconductor			X		X	X
Pandey	Sujan	Velinktech	X	X	X	X	X	X

Park	Pusik	Korea Electronics Technology Institute (KETI)	X	X	X	X	X	X
Rajagopal	Karthik	Texas Instruments Inc.					X	X
Regev	Alon	Keysight Technologies	X	X	X	X	X	X
Schedl	Anton	BMW Group	X	X	X	X	X	X
Sedarat	Hossein	Ethernovia			X	X		
Specht	Johannes	JSpecht Consulting		X	X	X		X
Strohmeier	Heiko	Robert Bosch GmbH	X	X		X	X	X
Sun	jingcong	Motorcomm Electronic Technology Co	X	X	X	X	X	X
Tan	Yuxuan	Motorcomm	X	X	X	X	X	X
Thomas	Rajan	Acsia Technologies					X	X
Thompson	Geoffrey	INDEPENDENT	X		X	X	X	X
Torres	Luisma	KD	X	X				
Turner	Max	Ethernovia			X	X	X	X
van Dyck	Peter	Infineon Technologies					X	X
Veloso Cauce	Gumersindo	BMW AG; BMW Group			X	X	X	X
Wang	Shun-Sheng	Realtek Semiconductor Corp.	X	X	X	X	X	
Wienckowski	Natalie	IVN Solutions LLC; Ethernovia, Bosch	X	X	X	X	X	X
Withey	James	Fluke	X	X				
Wu	Dance	Infineon Technologies			X	X	X	X
Zerna	Conrad	NXP Semiconductors						X
ZHU	YUE	Huawei Technologies Co., Ltd	X	X	X	X	X	X
Zhuang	Yan	Huawei Technologies Co., Ltd	X	X	X			